



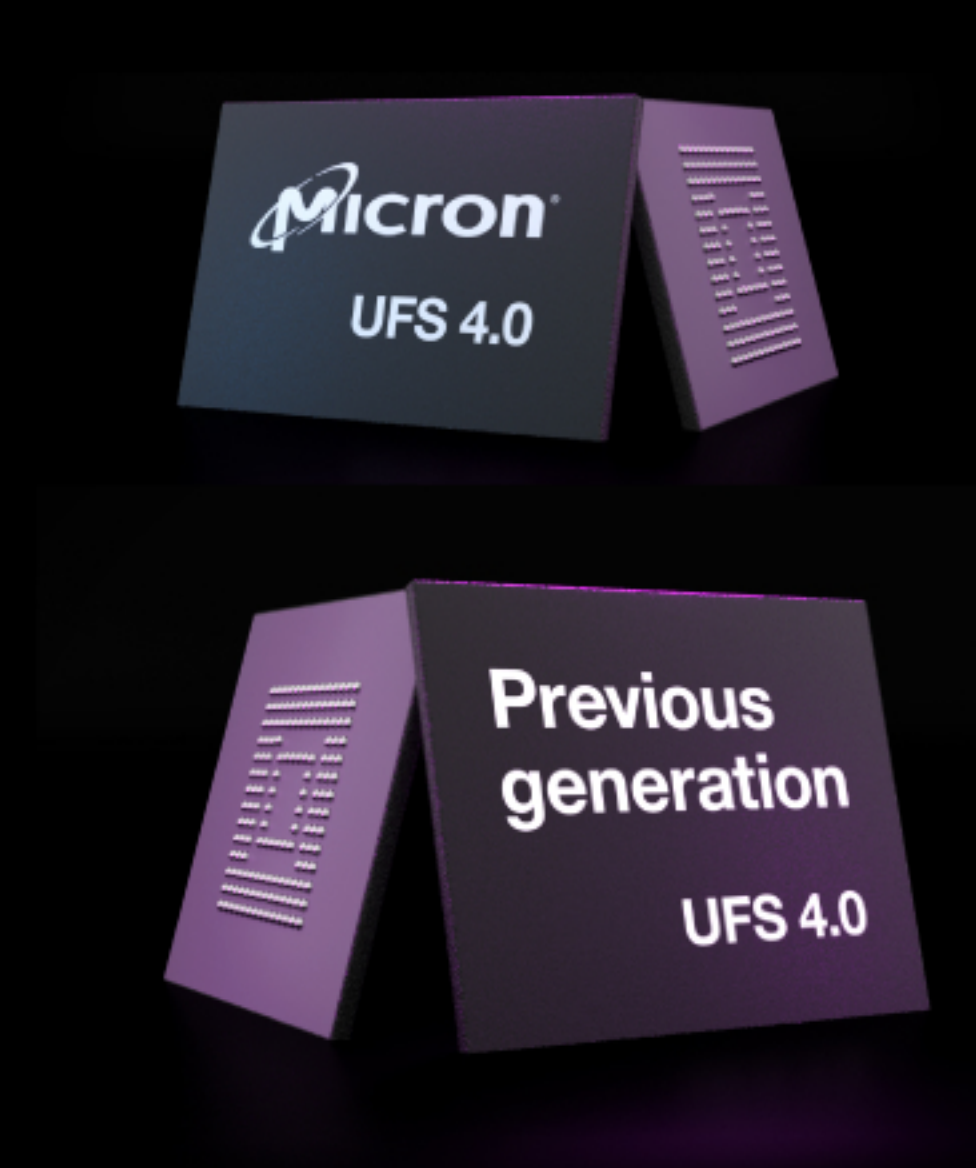
World's most compact UFS package¹ enabling next-generation phone designs and larger batteries

Key benefits

World's most compact managed NAND package size of 9x13 mm

Optimized package for next-generation foldable and ultra-slim smartphone designs

Custom firmware features to enhance end-user experiences



Delivering the world's leading mobile storage solutions

Best-in-class

UFS 4.0

- Available in capacities up to 1TB
- Designed on advanced 232-Layer 3D NAND technology
- Optimized for next-generation AI use cases

Differentiated firmware features to accelerate data-rich experiences

HPM

High-performance mode

Over 25% faster when launching² multiple apps

OBR

One-button refresh

10% faster³ app launches and snappy camera roll access

ZUFS

Zoned UFS

Improves the usefulness of the device over time

UFS 4.0 with an optimized, dependable and high-quality storage solution for smartphones



25+ years of mobile storage leadership



40% faster to load large language models⁴ (LLMs) at the edge



2x faster than the previous generation⁵ to launch apps faster



25% more power efficient than the previous generation⁶ to enable more scrolling between charges

Unlock the potential of UFS 4.0

To learn more about Micron's best-in-class UFS 4.0, visit micron.com/ufs

¹ As compared to publicly available UFS 4.0

² As compared to devices with UFS 4.0 without HPM enabled

³ As compared to devices with UFS 4.0 without OBR enabled

⁴ As compared to previous-generation UFS 3.1 176-layer NAND

⁵ As compared to previous-generation UFS 3.1 176-layer NAND

⁶ As compared to previous-generation UFS 3.1 176-layer NAND